


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/22/13164	
1.3 Title of PCN	STM32WB15 & STM32WB10 - product enhancement	
1.4 Product Category	STM32WB15 STM32WB10	
1.5 Issue date	2022-03-31	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC T14F Taiwan

4. Description of change

	Old	New
4.1 Description	<p>STM32WB15 and STM32WB10 - (Die494 - cut2.0 revision B) product has limitation as described in Errata Sheets.</p> <p>ES0557 (Rev 3 - June 2021) for STM32WB15 device: - (2.3.8) SMPS is functional only with Stop 0 and Run modes</p> <p>ES0556 (Rev 2 - June 2021) for STM32WB10 device: - in current version STM32WB10 product has no SMPS functionality</p>	<p>STM32WB15 and STM32WB10- (Die494 - cut2.1 revision Z) product enhancement fixes those limitations as described in Errata Sheets.</p> <p>ES0557 (Rev 4 – March 2022) for STM32WB15 device: - (2.3.8) SMPS is functional only with Stop 0 and Run modes - is now fixed on die revision Z</p> <p>ES0556 (Rev 3 - March 2022) for STM32WB10 device: - in new version STM32WB10 product has no SMPS functionality</p>
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionalities improvements as indicated in document ES0557 and ES0556	

5. Reason / motivation for change

5.1 Motivation	Improvements was implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST internal tools Die revision changes from "B" to "Z" on Package Marking.
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7. Timing / schedule

7.1 Date of qualification results	2022-02-09
7.2 Intended start of delivery	2022-04-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	13164 MDG-MCD-RERMCD1914 V1.1 STM32WB15 Tiny Dory 320K Die 494XXXZ evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-03-31

9. Attachments (additional documentations)
13164 Public product.pdf 13164 MDG-MCD-RERMCD1914 V1.1 STM32WB15 Tiny Dory 320K Die 494XXXZ evaluation report.pdf 13164 PCN13164_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32WB10CCU5	
	STM32WB15CCU6	
	STM32WB15CCU6E	

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